

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Siegfried HERRMANN	05/08/2009
Berthold HAHN	05/25/2009
RECEIVING PARTY DATA	
Name:	OSRAM Opto Semiconductors GmbH
Street Address:	Leibnizstrasse 4
City:	Regensburg
State/Country:	GERMANY
Postal Code:	93055
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12376425
CORRESPONDENCE DATA	
Fax Number:	(212)972-5487
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	212-687-2770
Email:	docket@cplplaw.com
Correspondent Name:	COHEN, PONTANI, LIEBERMAN & PAVANE LLP
Address Line 1:	551 FIFTH AVENUE
Address Line 2:	SUITE 1210
Address Line 4:	NEW YORK, NEW YORK 10176
ATTORNEY DOCKET NUMBER:	5367-462PUS
NAME OF SUBMITTER:	Thomas Langer
Total Attachments: 4 source=20090710110820#page1.tif source=20090710110820#page2.tif	

CH \$40.00 12376425

source=20090710110820#page3.tif

source=20090710110820#page4.tif

ASSIGNMENT

In consideration of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, We the undersigned, Siegfried HERRMANN, Berthold HAHN (hereinafter referred to as "ASSIGNOR"):

Hereby sell, assign and transfer to OSRAM Opto Semiconductors GmbH (hereinafter referred to as "ASSIGNEE"), a corporation of Germany, having a place of business at Leibnizstrasse 4, 93055 Regensburg, Germany, respectively, its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to the invention which is disclosed in the application for United States Letters Patent Serial No. 12/376,425, and which is entitled

THIN-FILM SEMICONDUCTOR COMPONENT AND COMPONENT ASSEMBLY

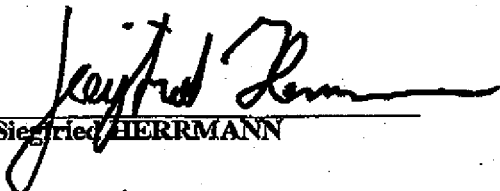
and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on said invention; and in and to all original, reissued and other patents and certificates of invention which have been or shall be issued in the United States and all foreign countries on said invention;

Agree that said Assignee may apply for and receive Letters Patent for said invention in its own name, and that, when requested, without further consideration from or charge to, but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on said invention; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee,

its successors, assigns, and representatives, all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said invention and for vesting title to said invention and all applications for patents and all patents on said invention, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: May/08/2009
month/day/year


Siegfried HERRMANN

Piedl
Witness
Walter Hahn
Witness

Date: _____
month/day/year

Berthold HAHN

Witness

Witness

Note: Signature of a witness is preferable but not required.

ASSIGNMENT

In consideration of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, We the undersigned, Siegfried HERRMANN, Borthold HAHN (hereinafter referred to as "ASSIGNOR"):

Hereby sell, assign and transfer to OSRAM Opto Semiconductors GmbH (hereinafter referred to as "ASSIGNEE"), a corporation of Germany, having a place of business at Leibnizstrasse 4, 93055 Regensburg, Germany, respectively, its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to the invention which is disclosed in the application for United States Letters Patent Serial No. 12/376,425, and which is entitled

THIN-FILM SEMICONDUCTOR COMPONENT AND COMPONENT ASSEMBLY

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on said invention; and in and to all original, reissued and other patents and certificates of invention which have been or shall be issued in the United States and all foreign countries on said invention;

Agree that said Assignee may apply for and receive Letters Patent for said invention in its own name, and that, when requested, without further consideration from or charge to, but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on said invention; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee,

its successors, assigns, and representatives, all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said invention and for vesting title to said invention and all applications for patents and all patents on said invention, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: _____
month/day/year

Siegfried HERRMANN

Witness

Witness

Date: 05/25/09
month/day/year



Berthold HAHN



Witness



Witness

Note: Signature of a witness is preferable but not required.